54F374

54F374 Octal D-Type Flip-Flop with TRI-STATE(RM) Outputs



Literature Number: SNOS190



54F/74F374 Octal D-Type Flip-Flop with TRI-STATE® Outputs

General Description

The 'F374 is a high-speed, low-power octal D-type flip-flop featuring separate D-type inputs for each flip-flop and TRI-STATE outputs for bus-oriented applications. A buffered Clock (CP) and Output Enable $(\overline{\text{OE}})$ are common to all flip-flops.

Features

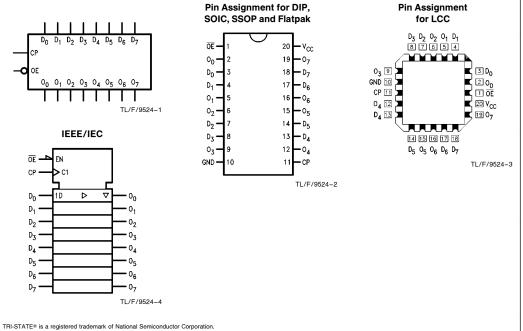
- Edge-triggered D-type inputs
- Buffered positive edge-triggered clock
- TRI-STATE outputs for bus-oriented applications
- Guaranteed 4000V minimum ESD protection

Commercial	Military	Package Number	Package Description
74F374PC		N20A	20-Lead (0.300" Wide) Molded Dual-In-Line
	54F374DM (QB)	J20A	20-Lead Ceramic Dual-In-Line
74F374SC (Note 1)		M20B	20-Lead (0.300" Wide) Molded Small Outline, JEDEC
74F374SJ (Note 1)		M20D	20-Lead (0.300" Wide) Molded Small Outline, EIAJ
74F374MSA (Note 1)		MSA20	20-Lead Molded Shrink Small Outline, EIAJ Type II
	54F374FM (QB)	W20A	20-Lead Cerpack
	54F374LM (QB)	E20A	20-Lead Ceramic Leadless Chip Carrier, Type C

Note 1: Devices also available in 13" reel. Use suffix = SCX, SJX, and MSAX.

Logic Symbols

Connection Diagrams



Unit Loading/Fan Out

Pin		54F/74F			
Names	Description	U.L. HIGH/LOW	Input I _{IH} /I _{IL} Output I _{OH} /I _{OL}		
D ₀ -D ₇ CP	Data Inputs Clock Pulse Input (Active Rising Edge)	1.0/1.0 1.0/1.0	20 μA/ – 0.6 mA 20 μA/ – 0.6 mA		
ŌĒ	TRI-STATE Output Enable Input (Active LOW)	1.0/1.0	20 μA/-0.6 mA		
00-07	TRI-STATE Outputs	150/40 (33.3)	-3 mA/24 mA (20 mA)		

Functional Description

The 'F374 consists of eight edge-triggered flip-flops with individual D-type inputs and TRI-STATE true outputs. The buffered clock and buffered Output Enable are common to all flip-flops. The eight flip-flops will store the state of their individual D inputs that meet the setup and hold time requirements on the LOW-to-HIGH Clock (CP) transition. With the Output Enable (OE) LOW, the contents of the eight flipflops are available at the outputs. When the $\overline{\text{OE}}$ is HIGH, the outputs go to the high impedance state. Operation of the OE input does not affected the state of the flip-flops.

Truth Table

	Inputs		Internal	Output		
D _n	СР	ŌĒ	Register	On		
Н	\	L	Н	Н		
L	_	L	L	L		
Χ	Χ	Н	X	z		

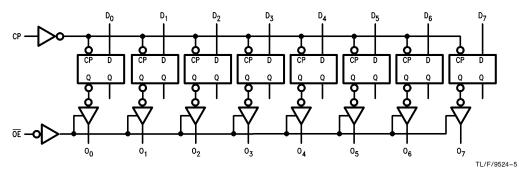
H = HIGH Voltage Level L = LOW Voltage Level

= Immaterial

Z = High Impedance

Z = LOW-to-HIGH Clock Transition

Logic Diagram



Please note that this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Absolute Maximum Ratings (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

 $\begin{array}{lll} \mbox{Storage Temperature} & -65^{\circ}\mbox{C to} + 150^{\circ}\mbox{C} \\ \mbox{Ambient Temperature under Bias} & -55^{\circ}\mbox{C to} + 125^{\circ}\mbox{C} \\ \mbox{Junction Temperature under Bias} & -55^{\circ}\mbox{C to} + 175^{\circ}\mbox{C} \\ \mbox{Plastic} & -55^{\circ}\mbox{C to} + 150^{\circ}\mbox{C} \\ \end{array}$

V_{CC} Pin Potential to

Input Current (Note 2) $$-30\ \text{mA}$\ \text{to}$\ +5.0\ \text{mA}$$

Voltage Applied to Output

in HIGH State (with $V_{CC} = 0V$)

 $\begin{array}{lll} \text{Standard Output} & -0.5 \text{V to V}_{\text{CC}} \\ \text{TRI-STATE Output} & -0.5 \text{V to } +5.5 \text{V} \end{array}$

Current Applied to Output

in LOW State (Max) twice the rated I_{OL} (mA)

ESD Last Passing Voltage (Min)

4000V

Note 1: Absolute maximum ratings are values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

Note 2: Either voltage limit or current limit is sufficient to protect inputs.

Recommended Operating Conditions

Free Air Ambient Temperature

Supply Voltage

Military + 4.5V to + 5.5V Commercial + 4.5V to + 5.5V

DC Electrical Characteristics

Symbol	Parameter		54F/74F			Units	Vcc	Conditions	
Symbol	Faranie	tei	Min	Тур	Max	Units	VCC	Conditions	
V _{IH}	Input HIGH Voltage		2.0			V		Recognized as a HIGH Signal	
V _{IL}	Input LOW Voltage				0.8	V		Recognized as a LOW Signal	
V _{CD}	Input Clamp Diode Vo	oltage			-1.2	V	Min	$I_{\text{IN}} = -18 \text{mA}$	
V _{OH}	Output HIGH Voltage	54F 10% V _{CC} 54F 10% V _{CC} 74F 10% V _{CC} 74F 10% V _{CC} 74F 5% V _{CC} 74F 5% V _{CC}	2.5 2.4 2.5 2.4 2.7 2.7			V	Min	$I_{OH} = -1 \text{ mA}$ $I_{OH} = -3 \text{ mA}$ $I_{OH} = -1 \text{ mA}$ $I_{OH} = -3 \text{ mA}$ $I_{OH} = -1 \text{ mA}$ $I_{OH} = -3 \text{ mA}$	
V _{OL}	Output LOW Voltage	54F 10% V _{CC} 74F 10% V _{CC}			0.5 0.5	V	Min	I _{OL} = 20 mA I _{OL} = 24 mA	
I _{IH}	Input HIGH Current	54F 74F			20.0 5.0	μΑ	Max	V _{IN} = 2.7V	
I _{BVI}	Input HIGH Current Breakdown Test	54F 74F			100 7.0	μΑ	Max	V _{IN} = 7.0V	
I _{CEX}	Output HIGH Leakage Current	54F 74F			250 50	μΑ	Max	$V_{OUT} = V_{CC}$	
V _{ID}	Input Leakage Test	74F	4.75			٧	0.0	$I_{\text{ID}} = 1.9 \mu\text{A}$ All Other Pins Grounded	
I _{OD}	Output Leakage Circuit Current	74F			3.75	μΑ	0.0	V _{IOD} = 150 mV All Other Pins Grounded	
I _{IL}	Input LOW Current				-0.6	mA	Max	V _{IN} = 0.5V	
lozh	Output Leakage Curr	ent			50	μΑ	Max	V _{OUT} = 2.7V	
l _{OZL}	Output Leakage Current				-50	μΑ	Max	V _{OUT} = 0.5V	
los	Output Short-Circuit Current		-60		-150	mA	Max	V _{OUT} = 0V	
I _{ZZ}	Bus Drainage Test				500	μΑ	0.0V	V _{OUT} = 5.25V	
lccz	Power Supply Current			55	86	mA	Max	V _O = HIGH Z	

AC Electrical Characteristics

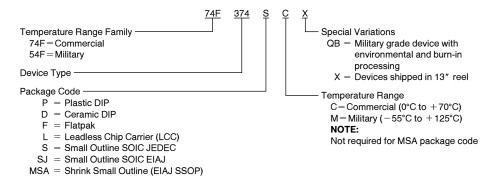
		$74F$ $T_{A} = +25^{\circ}C$ $V_{CC} = +5.0V$ $C_{L} = 50 pF$			54F T _A , V _{CC} = Mil C _L = 50 pF		74F T _A , V _{CC} = Com C _L = 50 pF		Units
Symbol	Parameter								
		Min	Тур	Max	Min	Max	Min	Max	
f _{max}	Maximum Clock Frequency	100	140		60		70		MHz
t _{PLH} t _{PHL}	Propagation Delay CP to O _n	4.0 4.0	6.5 6.5	8.5 8.5	4.0 4.0	10.5 11.0	4.0 4.0	10.0 10.0	ns
t _{PZH}	Output Enable Time	2.0 2.0	9.0 5.8	11.5 7.5	2.0 2.0	14.0 10.0	2.0 2.0	12.5 8.5	- ns
t _{PHZ}	Output Disable Time	2.0 1.5	5.3 4.3	7.0 5.5	2.0 1.5	8.0 7.5	2.0 1.5	8.0 6.5	113

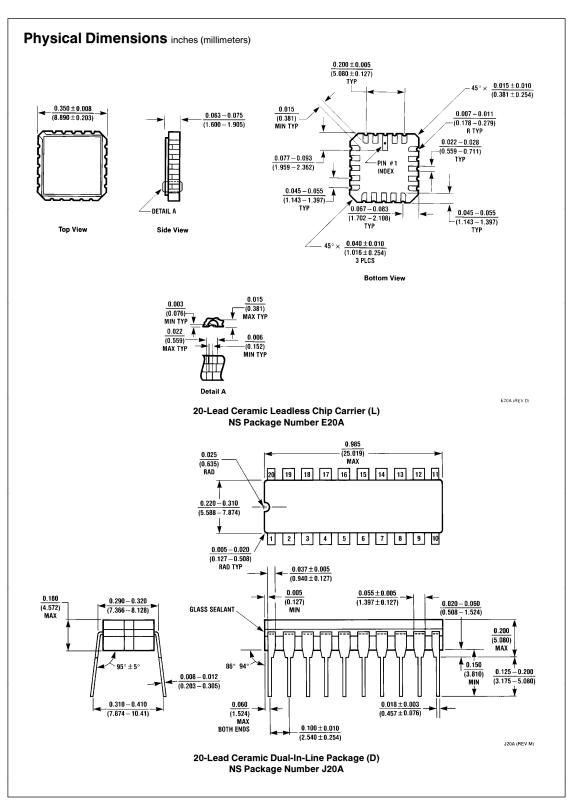
AC Operating Requirements

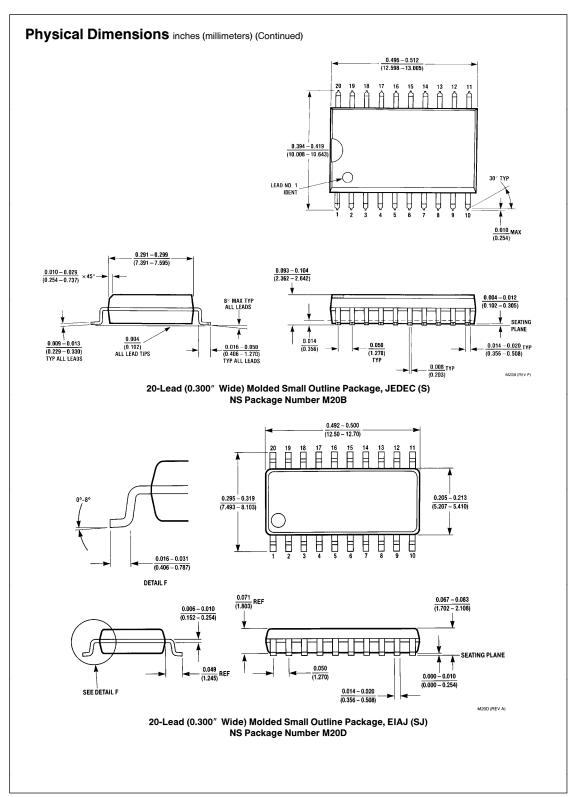
		$74F$ $T_A = +25^{\circ}C$ $V_{CC} = +5.0V$		54	IF	74F		
Symbol	Parameter			$T_A, V_{CC} = Mil$		$T_A, V_{CC} = Com$		Units
		Min	Max	Min	Max	Min	Max	
t _s (H) t _s (L)	Setup Time, HIGH or LOW D _n to CP	2.0 2.0		2.5 2.0		2.0 2.0		ns
t _h (H)	Hold Time, HIGH or LOW D _n to CP	2.0 2.0		2.0 2.5		2.0 2.0		113
t _w (H)	CP Pulse Width HIGH or LOW	7.0 6.0		7.0 6.0		7.0 6.0		ns

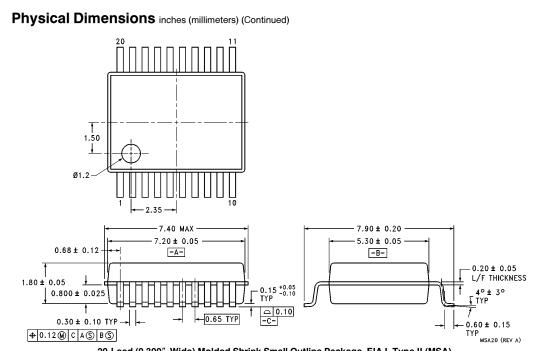
Ordering Information

The device number is used to form part of a simplified purchasing code where the package type and temperature range are defined as follows:

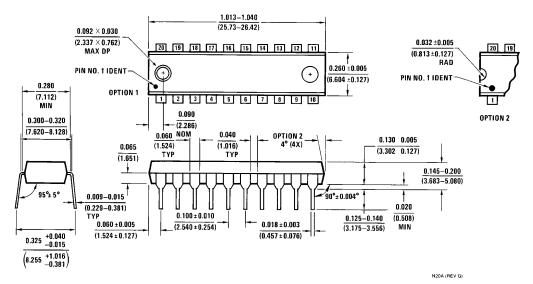






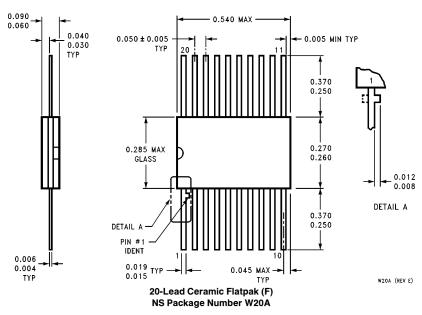


20-Lead (0.300" Wide) Molded Shrink Small Outline Package, EIAJ, Type II (MSA) NS Package Number MSA20



20-Lead (0.300" Wide) Molded Dual-In-Line Package (P) NS Package Number N20A

Physical Dimensions inches (millimeters) (Continued)



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